School of Engineering THERMAL ANALYSIS OF NEW TRANSDERMAL DEVICES ICP Institute of FOR POWER TRANSFER TO VENTRICULAR ASSIST DEVICES **Computational Physics**



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INTRODUCTION

The gold-standard approach of Ventricular Assist Devices (VADs) involves using insulated transcutaneous metallic drivelines to deliver power from the external battery through the abdominal wall to the pump in the upper abdomen. However, VAD drivelines can negatively affect wound healing, leading to driveline infections (DLI) in about 1 out of 5 patients within the first year of implantation [1], due to biofilm formation in the skin's upper layers (Fig. 1).

NEW TRANSDERMAL DEVICE FOR VADs

Current VAD drivelines

- Large-diameter (6-8 mm)
- Severe inflammatory reactions
- Frequent epidermal downgrowth

Transdermal wires

- 0.2 mm diameter
- Milder inflammatory responses
- Restricted epidermal downgrowth
- Improved mechanical adhesion
- Silicone and polyurethane coated wires

To promote healing of small wounds by minimizing wire impact on the



Fig. 1: Illustration of VAD and driveline infection. Adapted from [1], [2]

skin interface and reduce DLI (Fig. 2), we propose a novel approach involving embedding a set of 0.2 mm diameter copper wires with polyurethane (PU) coating into a polymer-based material for VAD drivelines.



THERMAL ANALYSIS SIMULATIONS

We investigated the electrothermal implications of conductive wires on the human body through 3D COMSOL skin model simulations (Fig. 3) representing the epidermis, dermis, fat, and muscle [4]. Additionally, a PDMS layer was included in the model to represent the silicon-based material of the conductive skin. Various PU insulating coating thicknesses were tested on a 0.2 mm diameter copper wire.

- Increasing the insulation layer did not lead to a significant improvement in the skin model.
- The observed temperature difference in the model arose from the temperature skin gradient rather than the electric current (Fig. 4).
- The inrush current causes a temporary 0.42°C increase in the core temperature of the copper wires (Fig. 5).
- In the steady state, both wire core and PDMS temperatures remain elevated by around 0.08°C and 0.03°C, respectively

